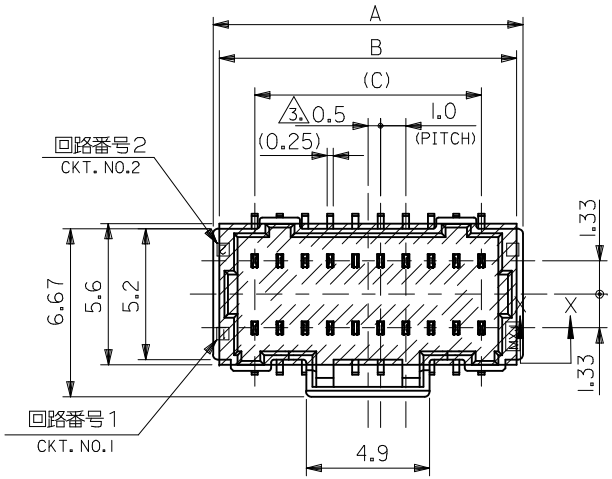
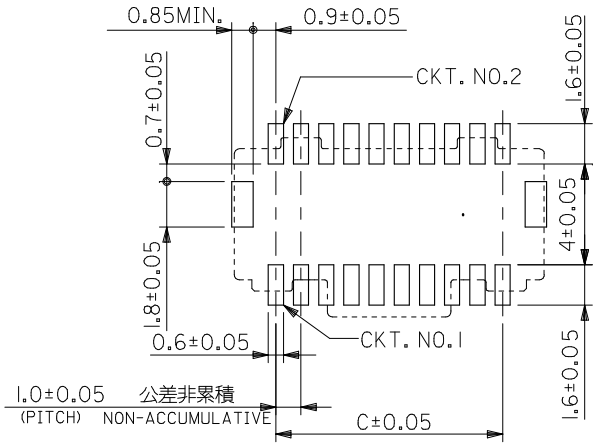
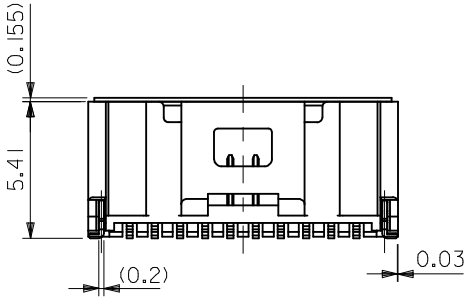
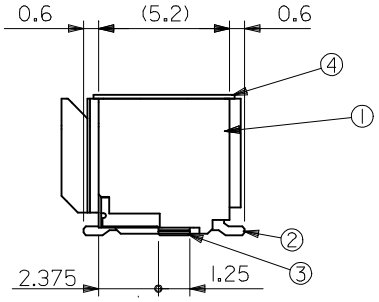
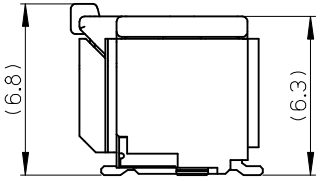




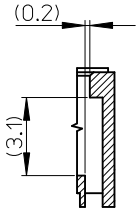
参考パターンレイアウト
RECCOMENDED PATTERN DIM. (REF.)







嵌合高さ
MATING HEIGHT



SECTION X-X

番号 NO.	部品 PART	材質 MATERIAL
①	ウエハー WAFER	耐熱ナイロン，UL94V-0，色：シート2参照 HEAT RESISTANCE NYLON, UL94V-0, COLOR: SEE SHEET 2
②	ソルダーピン SOLDER PIN	りん青銅 PHOSPHOR BRONZE 金メッキ：0．1μmMIN. GOLD ニッケルメッキ（下地）：1．0μmMIN. NICKEL(UNDER PLATING)
③	ネイル NAIL	りん青銅 PHOSPHOR BRONZE 錫メッキ：1．0μmMIN. TIN ニッケルメッキ（下地）：1．0μmMIN. NICKEL(UNDER PLATING)
④	カバーテープ COVER TAPE	ポリイミドテープ POLYIMIDE TAPE

NOTES.
1．嵌合相手：501189-****
MATE WITH：501189-****
2．ソルダーピン及びネイル平坦度は、0．1MAX.
SOLDER PIN AND NAIL COPLANARITY TO BE 0.1MAX.
3. 極数／2＝偶数に適用
APPLY FOR CKT SIZE/2=EVEN
4．ELV 及び RoHS 適合品
ELV AND RoHS COMPLIANT.

カバーテープの有無 COVER TAPE	C	B	A	オーダー番号 ORDER NO.		CONNECTOR SERIES NO.	CKT
無 NO	24		27.3	501190-5027	501190-5029		50
	19		22.3	501190-4027	501190-4029		40
	14		17.3	501190-3027	501190-3029		30
	9		12.3	501190-2027	501190-2029		20
有 YES	24	26.8	27.3	501190-5017	501190-5019		50
	19	21.8	22.3	501190-4017	501190-4019		40
				501190-405*	501190-407*		
	14	16.8	17.3	501190-3017	501190-3019		30
				501190-305*	501190-307*		
	9	11.8	12.3	501190-2017	501190-2019		20
				501190-205*	501190-207*		

REVISED
EC NO: J2014-1175 2013/11/22
DRWN:RHORI 2013/11/25
CH'KD:KASAKAWA 2014/01/28
APPR:NUKITA
DESCRIPTION
REV

GENERAL TOLERANCES (UNLESS SPECIFIED)

10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR	±3 °

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: 5:1
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY: NYOSHIDA DATE: 2004/12/17
CHECKED BY: MYAGI DATE: 2004/12/17
APPROVED BY: ANODA DATE: 2004/12/17

TITLE: 1.0 WIRE TO BOARD CONN. WAFER ASS'Y (2-ROW S/T) -LEAD FREE-

MATERIAL NO.: SEE CHART
DOCUMENT NO.: SD-501190-003
SHEET NO.: 1 OF 2
SIZE: A3

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

	緑 GREEN	青 BLUE	赤 RED	黒 BLACK	色 COLOR	
有 YES	—//—	—//—	—//—	—//—	50	501190-**7*
	501190-4056	501190-4054	501190-4052	501190-4051	40	
	501190-3056	501190-3054	501190-3052	501190-3051	30	
	501190-2056	501190-2054	501190-2052	501190-2051	20	
COVER TAPE	EMBOSSED PACKAGE オーダー番号 ORDER NO.				CKT.	CONNECTOR SERIES NO.

	自然色 NATURAL	色 COLOR	
無 NO	501190-5027	50	501190-**29
	501190-4027	40	
	501190-3027	30	
	501190-2027	20	
COVER TAPE	EMBOSSED PACKAGE オーダー番号 ORDER NO.	CKT.	CONNECTOR SERIES NO.

	自然色 NATURAL	色 COLOR	
有 YES	501190-5017	50	501190-**19
	501190-4017	40	
	501190-3017	30	
	501190-2017	20	
COVER TAPE	EMBOSSED PACKAGE オーダー番号 ORDER NO.	CKT.	CONNECTOR SERIES NO.

SEE SHEET 1
EC NO: J2014-1175 2013/11/22
DRWN:RHORI 2013/11/25
CH'KD:KASAKAWA 2014/01/28
APPR:NUKITA
DESCRIPTION
REV

GENERAL TOLERANCES (UNLESS SPECIFIED)

10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR ±3 °	

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: 5:1
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

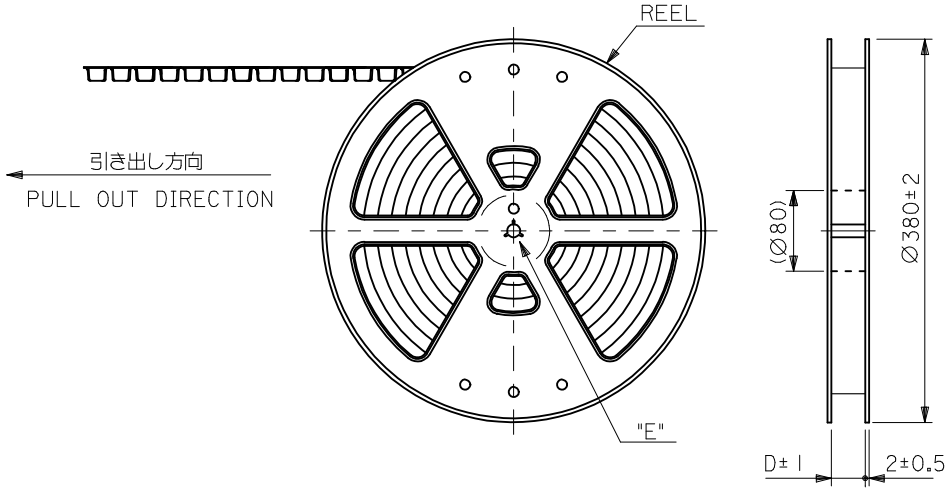
DRAWN BY: NYOSHIDA DATE: 2004/12/17
CHECKED BY: MYAGI DATE: 2004/12/17
APPROVED BY: ANODA DATE: 2004/12/17

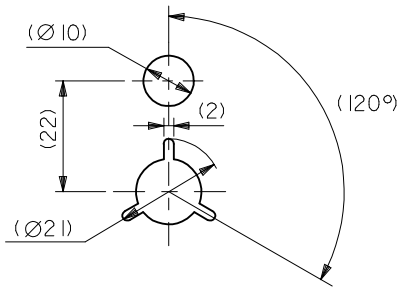
TITLE: 1.0 WIRE TO BOARD CONN. WAFER ASS'Y (2-ROW S/T) -LEAD FREE-

molex

MATERIAL NO.: SEE CHART
DOCUMENT NO.: SD-501190-003
SHEET NO.: 2 OF 2
SIZE: A3

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

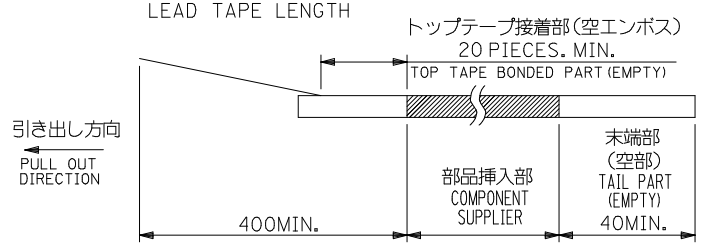




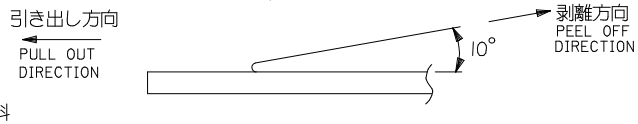
DETAIL "E"

NOTES

1. 製品詳細寸法については SD-501190-003 を参照ください。
   RE DETAILED DIMENSION, SEE SD-501190-003
2. 梱包数量：１１００個／リール
   NUMBER OF CONNECTORS : 1100PIECES/REEL
3. リードテープ長さ
   LEAD TAPE LENGTH



4. トップテープの剥離強度：0.1～1.3N{10.2 ～ 132.5gf}(剥離方向は下図参照)
   PEELING OFF FORCE OF TOP TAPE
   (PEELING DIRECTION AS SHOWN IN FOLLOWING FIGURE)
   尚、本規格値は、出荷時に適用。（但し、輸送時に剥離が発生しないこと）
   THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
   PEEL OFF SHOULD NOT BE ALLOWED, DURING TARANSPORTION.



5. 材料
   MATERIAL
   キャリアテープ：ポリプロピレン
   CARRIER TAPE:POLYPROPYLENE
   トップテープ：PET, PE, REF
   TOP TAPE
   リール：ポリスチレン〈リサイクル材を含む〉
   REEL : POLYSTYRENE <RECYCLE MATERIAL CONTAINED>
6. 乾燥剤入り防湿梱包仕様になります．(501190-**17, 501190-**27以外)
   INCLUDING DESICCANT TAPING PACKAGE.
   (BESIDES 501190-**17, 501190-**27)
7. ELV 及び RoHS 適合品
   ELV AND RoHS COMPLIANT.

REVISED			
EC NO: J2013-1460	DRWN:KWASHIO	CHKD:KASAKAWA	APPR:NUKITA
2013/06/12	2013/06/12	2013/06/12	DESCRIPTION
D			REV

GENERAL TOLERANCES (UNLESS SPECIFIED)	
10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR ±3 °	

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE	SCALE	DESIGN UNITS	
MM ONLY	---	METRIC	THIRD ANGLE PROJECTION

DRAWN BY	DATE
NYOSHIDA	2004/12/17
CHECKED BY	DATE
MYAGI	2004/12/17
APPROVED BY	DATE
ANODA	2004/12/17

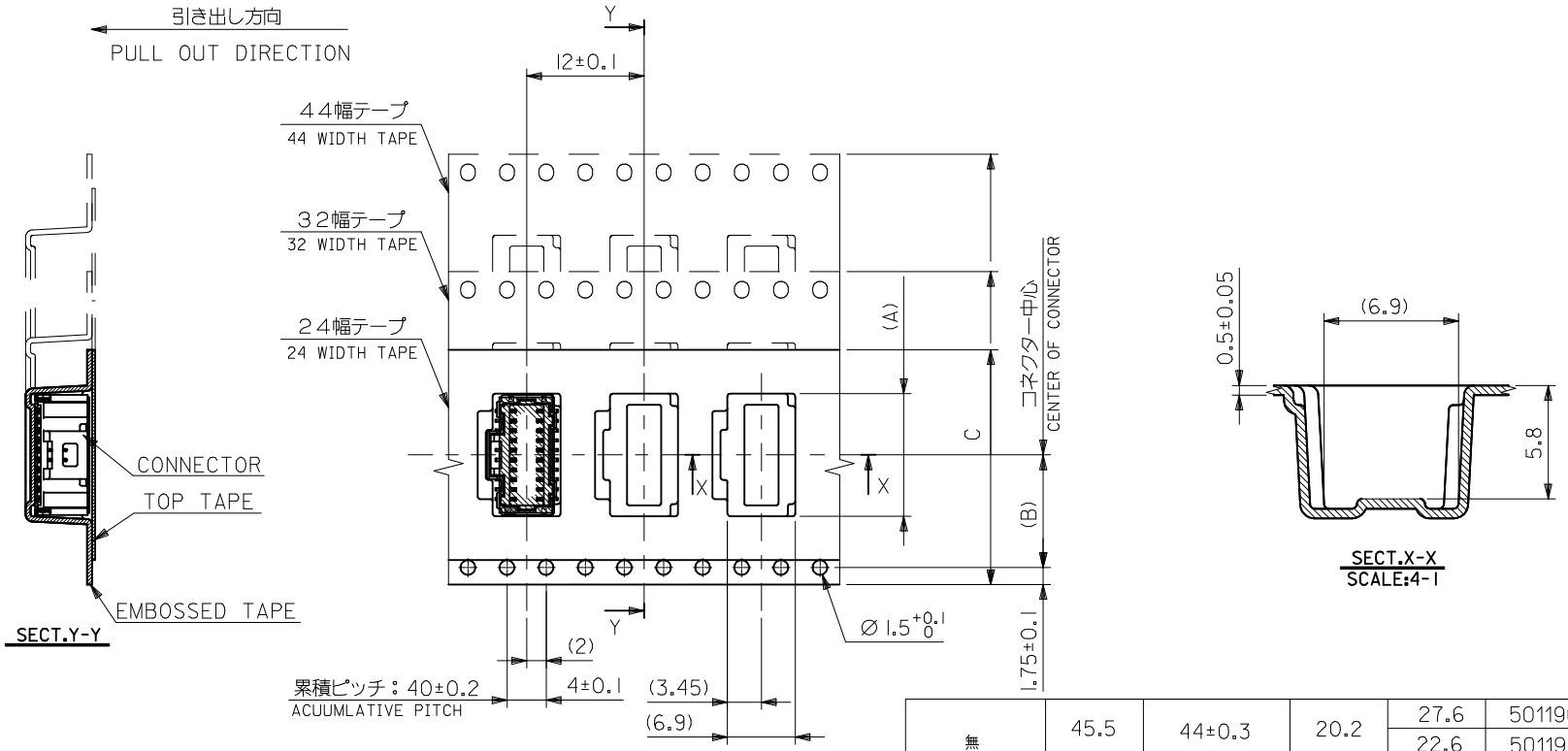
TITLE: 1.0 WIRE TO BOARD CONN. WAFER ASS'Y (2-ROW S/T) EMBTP PKG -LEAD FREE-

molex

MATERIAL NO.	DOCUMENT NO.	SHEET NO.
SEE SHEET 2	SD-501190-004	1 OF 3

SIZE A3

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION



吸着用カバーテープの有無 COVER TAPE	D	C CARRIER TAPE WIDTH	(B)	(A)	CONNECTOR SERIES NO.	EMBOSSED PACKAGE オーダー番号 ORDER NO.	CKTS.
無 NO	45.5	44±0.3	20.2	27.6	501190-5029	501190-5027	50
				22.6	501190-4029	501190-4027	40
	33.5	32±0.3	14.2	17.6	501190-3029	501190-3027	30
	25.5	24±0.3	11.5	12.6	501190-2029	501190-2027	20
有 YES	45.5	44±0.3	20.2	27.6	501190-5019	501190-5017	50
				22.6	501190-4019	501190-4017	40
					501190-407*	501190-405*	
	33.5	32±0.3	14.2	17.6	501190-3019	501190-3017	30
					501190-307*	501190-305*	
	25.5	24±0.3	11.5	12.6	501190-2019	501190-2017	20
					501190-207*	501190-205*	

REVISED
EC NO: J2013-1460 2013/06/12
DRWN:KWASHIO 2013/06/12
CH'KD:KASAKAWA 2013/06/12
APPR:NUKITA 2013/06/12
DESCRIPTION
D
REV

GENERAL TOLERANCES (UNLESS SPECIFIED)

10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR	±3 °

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: ---
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY: NYOSHIDA DATE: 2004/12/17
CHECKED BY: MYAGI DATE: 2004/12/17
APPROVED BY: ANODA DATE: 2004/12/17

TITLE: 1.0 WIRE TO BOARD CONN. WAFER ASS'Y (2-ROW S/T) EMBTP PKG -LEAD FREE-

molex

MATERIAL NO.: SEE CHART
DOCUMENT NO.: SD-501190-004
SHEET NO.: 2 OF 3
SIZE: A3

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

	緑 GREEN	青 BLUE	赤 RED	黒 BLACK	色 COLOR	
有 YES	—//—	—//—	—//—	—//—	50	501190-**7*
	501190-4056	501190-4054	501190-4052	501190-4051	40	
	501190-3056	501190-3054	501190-3052	501190-3051	30	
	501190-2056	501190-2054	501190-2052	501190-2051	20	
COVER TAPE	EMBOSSED PACKAGE オーダー番号 ORDER NO.				CKT.	CONNECTOR SERIES NO.

	自然色 NATURAL	色 COLOR	
無 NO	501190-5027	50	501190-**29
	501190-4027	40	
	501190-3027	30	
	501190-2027	20	
COVER TAPE	EMBOSSED PACKAGE オーダー番号 ORDER NO.	CKT.	CONNECTOR SERIES NO.

	自然色 NATURAL	色 COLOR	
有 YES	501190-5017	50	501190-**19
	501190-4017	40	
	501190-3017	30	
	501190-2017	20	
COVER TAPE	EMBOSSED PACKAGE オーダー番号 ORDER NO.	CKT.	CONNECTOR SERIES NO.

SEE SHEET 1
EC NO: J2013-1460 2013/06/12
DRWN:KWASHIO 2013/06/12
CH'KD:KASAKAWA 2013/06/12
APPR:NUKITA 2013/06/12
DESCRIPTION
REV
D

GENERAL TOLERANCES (UNLESS SPECIFIED)

10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR ±3 °	

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: ---
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY: NYOSHIDA DATE: 2004/12/17
CHECKED BY: MYAGI DATE: 2004/12/17
APPROVED BY: ANODA DATE: 2004/12/17

TITLE: 1.0 WIRE TO BOARD CONN. WAFER ASS'Y (2-ROW S/T) EMBTP PKG -LEAD FREE-

molex

MATERIAL NO.: SEE CHART
DOCUMENT NO.: SD-501190-004
SHEET NO.: 3 OF 3
SIZE: A3

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